

METALLIC DAM AND METHOD OF FORMING THEREFOR

ABSTRACT

A processed printed circuit board (50 or 80) can include a predetermined area on a substrate (40) defined by a metallized trace pattern (26) and solder (32 or 62) applied to the metallized trace pattern to form a dam around the predetermined area. The board can further include an optional electronic component (22) such as a semiconductor die within the predetermined area along with a conformal coating (52 or 82) applied to the predetermined area. A conformal coating (95) can also be applied to a predetermined area where no components lie underneath.